SUBMINIATURE SOLID STATE LAMP

Part Number: KM2520EG/4ID

High Efficiency Red

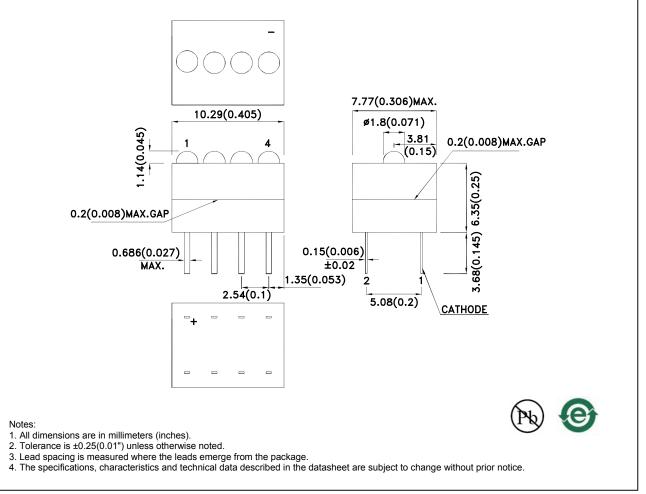
Features

- Black case enhances contrast.
- Vibration and shock resistant.
- Housing UL rating:94V-0.
- Housing material: type 66 nylon.
- RoHS compliant.

Description

The High Efficiency Red source color devices are made with Gallium Arsenide Phosphide on Gallium Phosphide Orange Light Emitting Diode.

Package Dimensions



SPEC NO: DSAD0556 APPROVED: WYNEC REV NO: V.10A CHECKED: Allen Liu DATE: APR/07/2013 DRAWN: F.Cui PAGE: 1 OF 5 ERP: 1102005298

Selection Guide Part No. Dice Lens Type

Faitino.	DICE				1
			Min.	Тур.	201/2
KM2520EG/4ID	High Efficiency Red (CaAsD/CaD)	Red Diffused	12	20	40°
KW2520EG/4ID	High Efficiency Red (GaAsP/GaP)	Red Dillused	*8	*16	

Notes:

1. θ 1/2 is the angle from optical centerline where the luminous intensity is 1/2 of the optical peak value.

Luminous intensity/ luminous Flux: +/-15%.
*Luminous intensity value is traceable to the CIE127-2007 compliant national standards.

Electrical / Optical Characteristics at TA=25°C

Symbol	Parameter	Device	Тур.	Max.	Units	Test Conditions
λpeak	Peak Wavelength	High Efficiency Red	627		nm	IF=20mA
λD [1]	Dominant Wavelength	High Efficiency Red	617		nm	IF=20mA
Δλ1/2	Spectral Line Half-width	High Efficiency Red	45		nm	IF=20mA
С	Capacitance	High Efficiency Red	15		pF	VF=0V;f=1MHz
VF [2]	Forward Voltage	High Efficiency Red	2	2.5	V	I⊧=20mA
lr	Reverse Current	High Efficiency Red		10	uA	VR = 5V

Notes:

1.Wavelength: +/-1nm. 2. Forward Voltage: +/-0.1V.

3. Wavelength value is traceable to the CIE127-2007 compliant national standards.

Absolute Maximum Ratings at TA=25°C

High Efficiency Red	Units	
75	mW	
30	mA	
160	mA	
5	V	
-40°C To +85°C		
260°C For 3 Seconds		
260°C For 5 Seconds		
	75 30 160 5 -40°C To +85°C 260°C For 3 Seconds	

Notes:

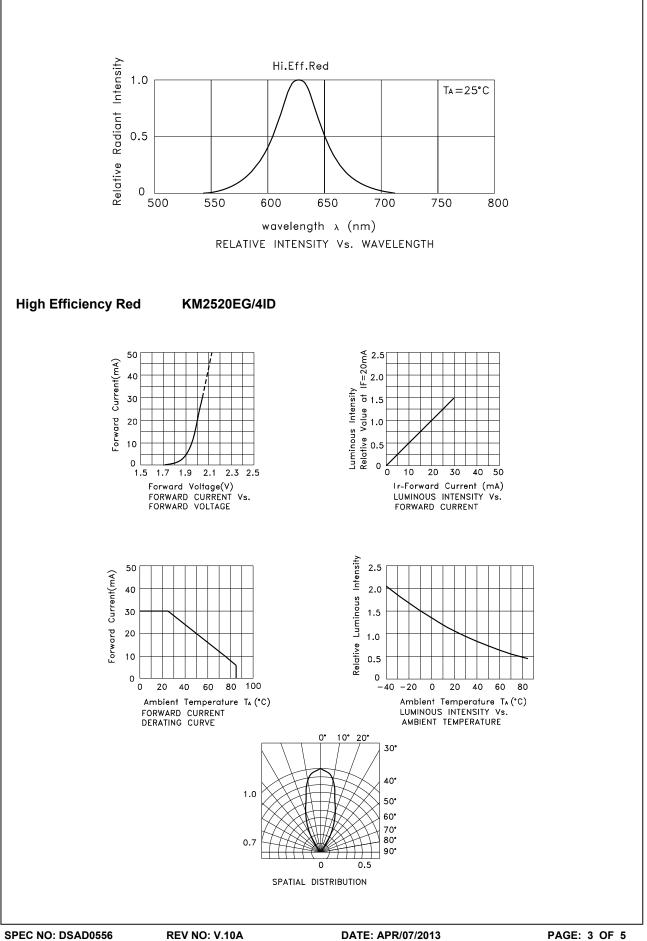
1. 1/10 Duty Cycle, 0.1ms Pulse Width.

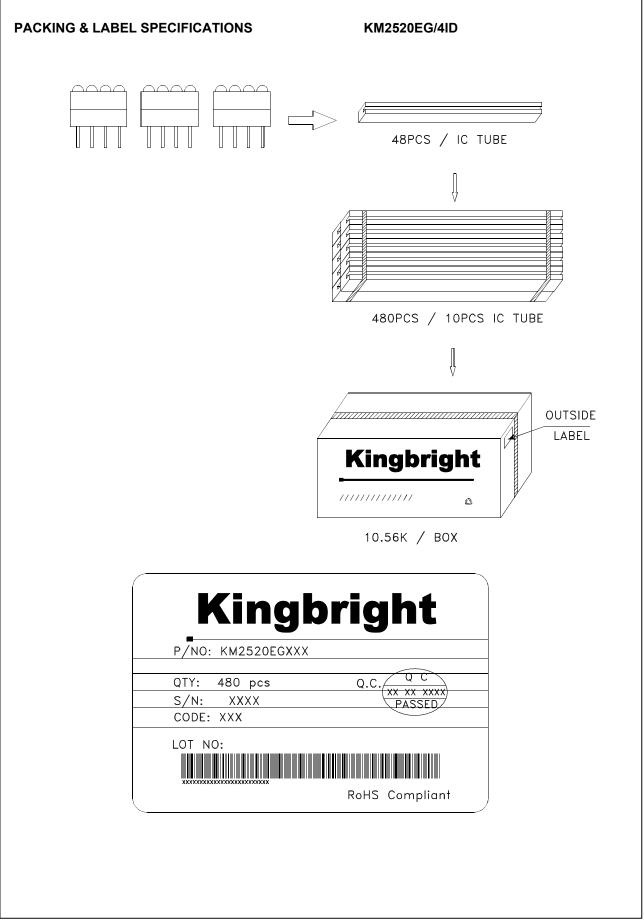
2. 2mm below package base.
3. 5mm below package base.

Viewing

Angle [1]

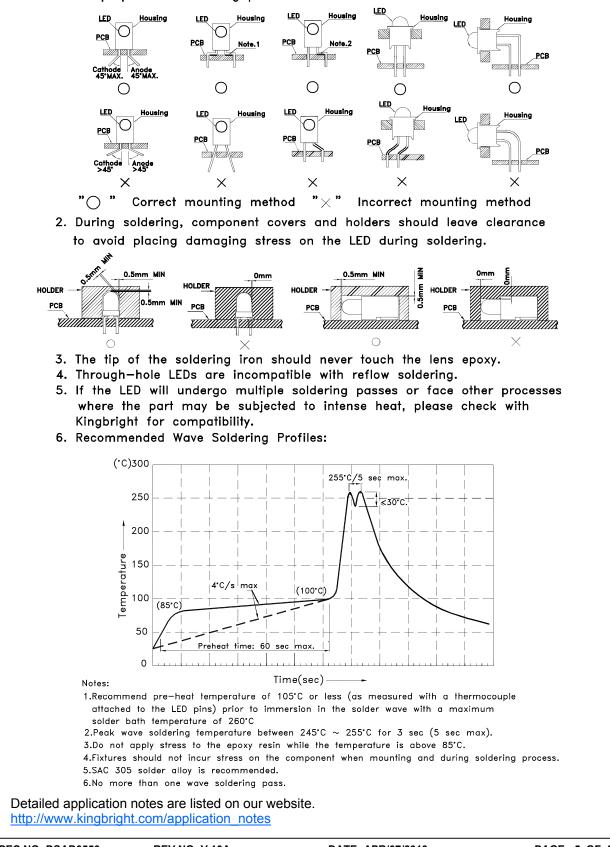
lv (mcd) [2] @ 20mA





PRECAUTIONS

1. The lead pitch of the LED must match the pitch of the mounting holes on the PCB during component placement. Lead-forming may be required to insure the lead pitch matches the hole pitch. Refer to the figure below for proper lead forming procedures.



DATE: APR/07/2013 DRAWN: F.Cui